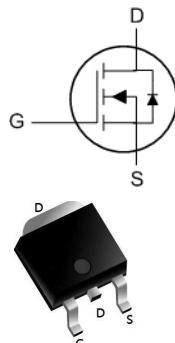


### Description

The 15N10 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The 15N10 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Super Low Gate Charge  
Green Device Available  
Excellent Cdv/dt effect decline  
Advanced high cell density Trench technology



### Product Summary

BVDSS	RDS(on)	ID
100V	85mΩ	15 A

### Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>c</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	15	A
I <sub>D</sub> @T <sub>c</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	8	A
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	3	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	2.4	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	20	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	6.1	mJ
I <sub>AS</sub>	Avalanche Current	10	A
P <sub>D</sub> @T <sub>c</sub> =25°C	Total Power Dissipation <sup>3</sup>	30	W
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>3</sup>	2	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	6.6	°C/W

# 15N10

Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	100	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=100\text{V}$ , $V_{GS}=0\text{V}$ ,	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{on})}$ <small>note3</small>	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$ , $I_D=5\text{A}$	-	85	110	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=3\text{A}$	-	96	140	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=25\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	765	-	pF
$C_{oss}$	Output Capacitance		-	38	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	33	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=50\text{V}$ , $I_D=2\text{A}$ , $V_{GS}=10\text{V}$	-	18	-	nC
$Q_{gs}$	Gate-Source Charge		-	2.5	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	4	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=50\text{V}$ , $I_D=3\text{A}$ , $R_G=1.8\Omega$ , $V_{GS}=10\text{V}$	-	7.5	-	ns
$t_r$	Turn-on Rise Time		-	6	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	21	-	ns
$t_f$	Turn-off Fall Time		-	9	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	10	-	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	40	-	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_S=10\text{A}$	-	-	1.2	V
$trr$	Body Diode Reverse Recovery Time	$I_F=3\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	-	21	-	ns
$Qrr$	Body Diode Reverse Recovery Charge		-	22	-	nC

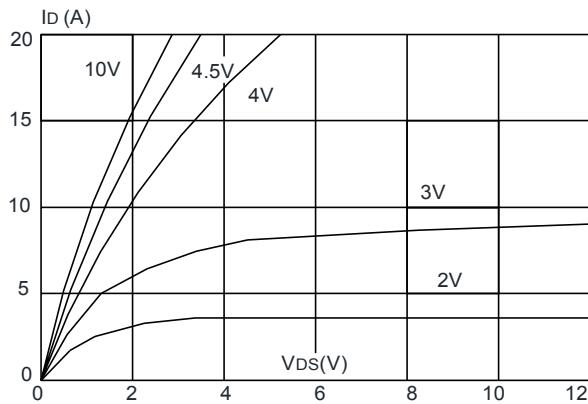
Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{DD}=30\text{V}$ ,  $V_G=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_g=25\Omega$ ,  $I_{AS}=4\text{A}$

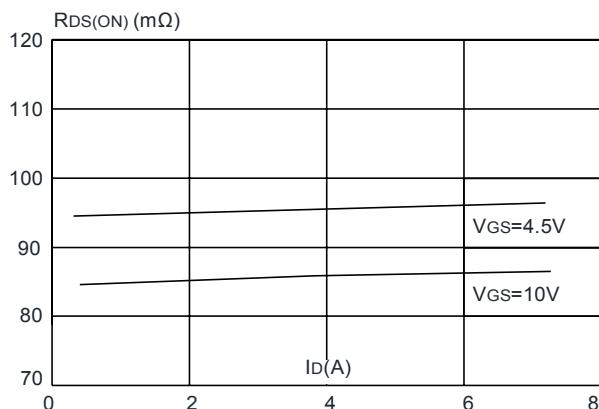
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$

## RATING AND CHARACTERISTIC CURVES (15N10)

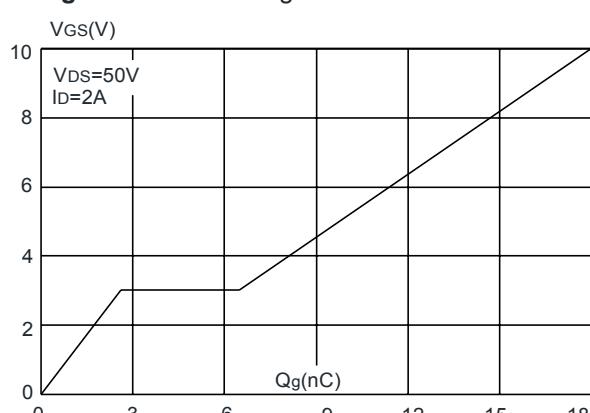
**Figure 1:** Output Characteristics



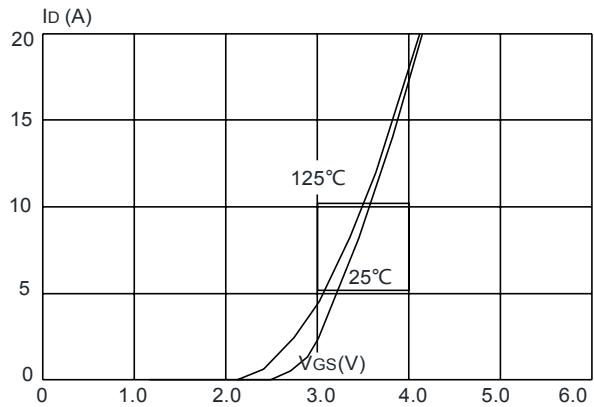
**Figure 3:** On-resistance vs. Drain Current



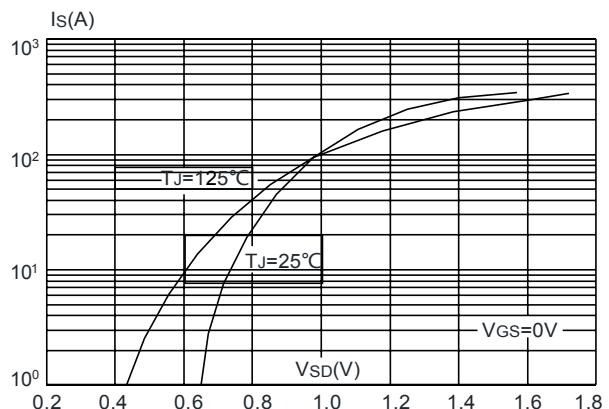
**Figure 5: Gate Charge Characteristics**



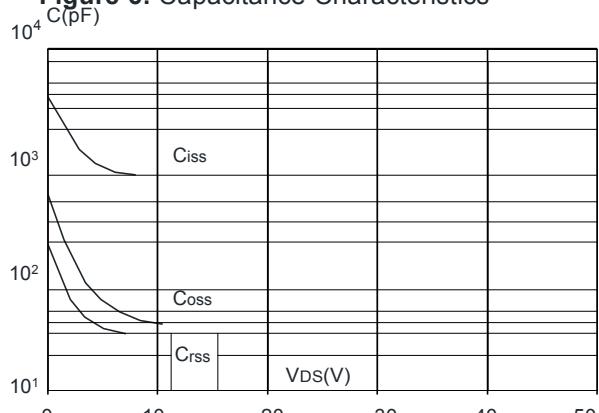
**Figure 2:** Typical Transfer Characteristics



**Figure 4 : Body Diode Characteristics**

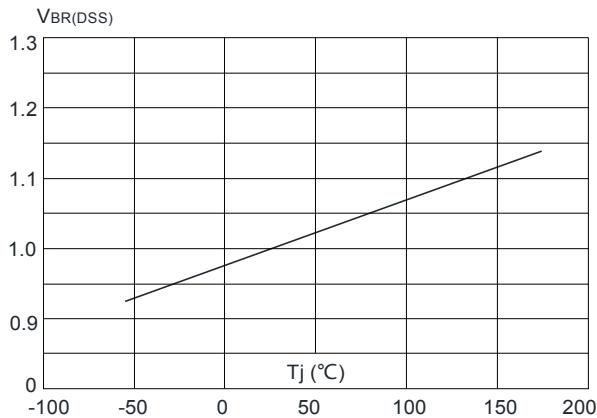


**Figure 6: Capacitance Characteristics**

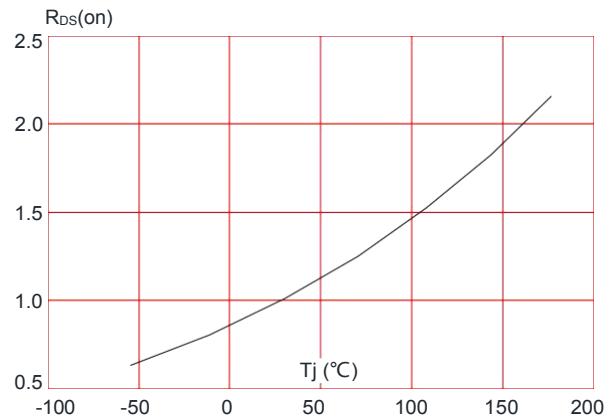


## RATING AND CHARACTERISTIC CURVES (15N10)

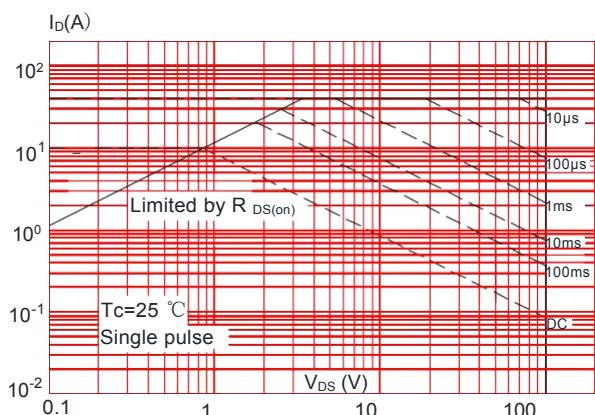
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



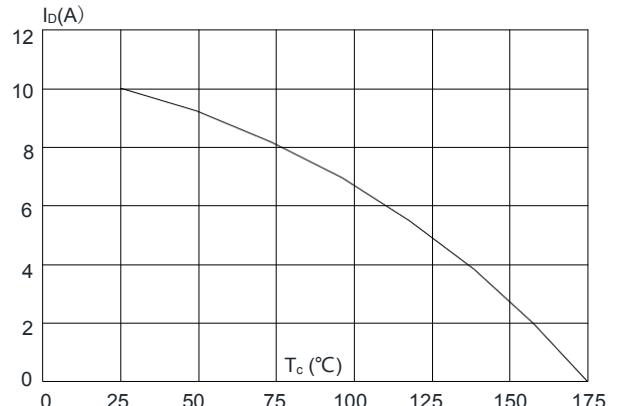
**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case

